

**CONTROL OF LINER THICKNESS FOR IMPROVING**  
**THERMAL CYCLE RELIABILITY**

**ABSTRACT OF THE DISCLOSURE**

5           A device, system and method for evaluating reliability  
of a semiconductor chip are disclosed. Strain is  
determined at a location of interest in a structure.  
Failures are evaluated in a plurality of the structures  
after stress cycling to determine a strain threshold with  
10       respect to a feature characteristic. Structures on a chip  
or chips are evaluated based on the feature characteristic  
to predict reliability based on the strain threshold and  
the feature characteristic. Predictions and design changes  
may be made based on the results.

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